

## GOSTONE PROHS



## GMS110N10F1

### N-Channel 100V,11mΩ max,SGT Power MOSFET

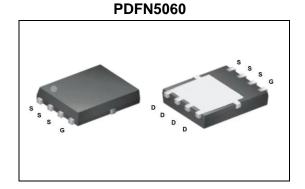
#### **Product Summary** V<sub>DS</sub> (V) $R_{DS(on),max}$ (m $\Omega$ ) $I_D(A)$ 11 @ V<sub>GS</sub> = 10V 61<sup>(1)</sup> 100

#### **Features**

- Low R<sub>DS(on)</sub> trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

#### **Application**

- DC/DC conversion
- Power switch
- Motor drives
- Synchronous Rectification in SMPS



# **GMXXXX** GS **FAYWWLT**

#### **PDFN5060**

NOTE: LOGO - GS

GMXXXXX- Part number code

F - Fab location code

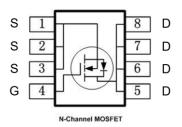
A - Assembly location code

Y - Year code

WW - Week code

L&T - Assembly lot code

#### **Equivalent circuit**



## Absolute maximum rating@25℃

Parameter			Limit	Unit
Drain-source voltage		V <sub>DS</sub>	100	V
Gate-source voltage		$V_{GS}$	±20	
	T <sub>C</sub> =25°C <sup>(1)</sup>		61	А
Continuous drain current	T <sub>C</sub> =100°C <sup>(1)</sup>	l <sub>D</sub>	39	
Pulsed drain current <sup>(2)</sup>		I <sub>D,pulse</sub>	194	
Avalanche energy, single pulse <sup>(3)</sup>		E <sub>AS</sub>	130	mJ
Down disable tion	Tc=25°C	D	74	W
Power dissipation	T <sub>A</sub> =100°C	P <sub>D</sub>	29	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

#### **Thermal Characteristic**

Parameter		Symbol	Max.	Unit	
Thermal resistance, junction-to-case	Steady state	Rejc	1.7	°C/\\/	
Thermal resistance, junction-to-ambient (4)	Steady state	Reja	45	°C/W	



## **Electrical Characteristics (TJ=25℃ unless otherwise noted)**

Parameter	Symbol	Test conditions	Min.	Тур.	Max.	Unit	
Static parameter							
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0, I <sub>D</sub> = 250 μA	100			V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.2	1.7	2.5	V	
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μA	
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		9.0	11	mΩ	
Forward transconductance (5)	$g_{fs}$	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 30 A		32		S	
Gate resistance	Rg	f = 1 MHz		1.2		Ω	
Dynamic <sup>(5)</sup>							
Total gate charge V <sub>GS</sub> = 10V	$Q_g$			18			
Total gate charge V <sub>GS</sub> = 4.5V	$Q_g$	$V_{DS} = 50 \text{ V}, I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}$		9.2		nC	
Gate-source charge	$Q_{gs}$	VDS - 30 V, ID - 20 A, VGS - 10 V		3.0			
Gate-drain charge	$Q_{gd}$			3.9			
Turn-on delay time	t <sub>d(on)</sub>			3.4			
Rise time	tr	$V_{DS} = 50 \text{ V}, I_{D} = 20 \text{ A}, V_{GS} = 10 \text{ V},$		3.5		ns	
Turn-off delay time	t <sub>d(off)</sub>	R <sub>GEN</sub> = 3 Ω		15			
Fall time	tf			8.5			
Input capacitance	C <sub>iss</sub>			1049			
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz		487		pF	
Reverse transfer capacitance	C <sub>rss</sub>			11			
Reverse Diode Characteristics (5)							
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>F</sub> = 2 A		0.7	1.2	V	
Reverse recovery time	t <sub>rr</sub>	1 = 20 A di/dt = 100 A/va		41		ns	
Reverse recovery charge	Qrr	$I_F = 20 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$		56		nC	

#### Notes

- (1) Limited by maximum junction temperature.
- (2) Pulse width limited by maximum junction temperature.
- (3)  $V_{DS} = 50 \text{ V}$ ,  $V_{GS} = 10 \text{ V}$ , L = 1.0 mH.
- (4) Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
- (5) Guaranteed by design, not subject to production testing.



## Typical Performance Characteristics

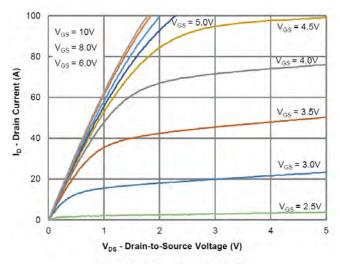


Figure 1: Output Characteristics

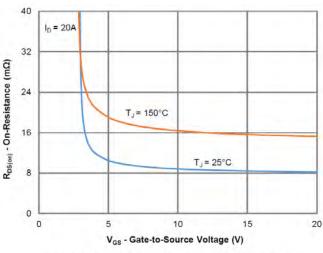


Figure 3: On-Resistance vs. Gate-Source Voltage

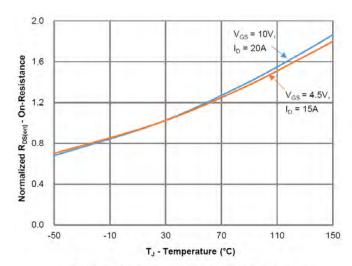


Figure 5: On-Resistance vs. Junction Temperature

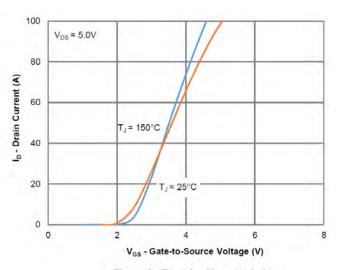


Figure 2: Transfer Characteristics

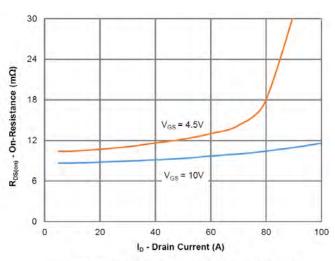


Figure 4: On-Resistance vs. Gate-Source Voltage

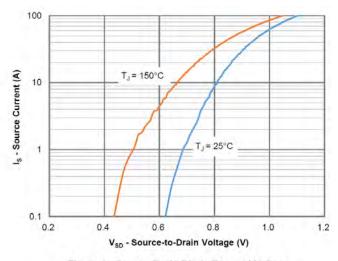


Figure 6: Source-Drain Diode Forward Voltage



## **Typical Performance Characteristics**

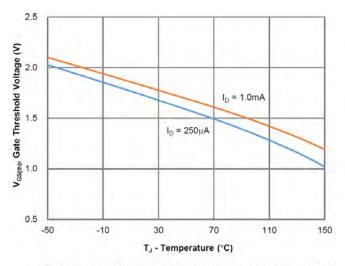


Figure 7: Gate Threshold Variation vs. Junction Temperature

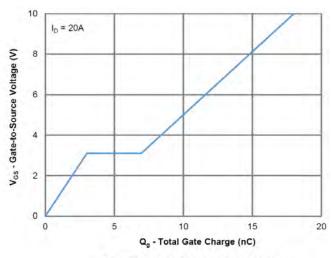


Figure 8: Gate Charge Characteristics

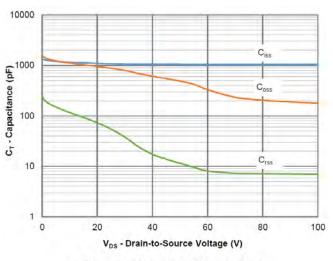


Figure 9: Capacitance Characteristics

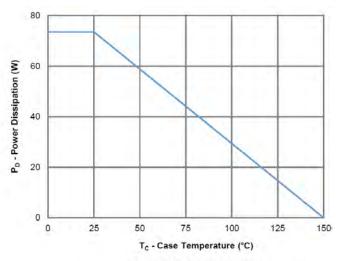


Figure 10: Power Derating

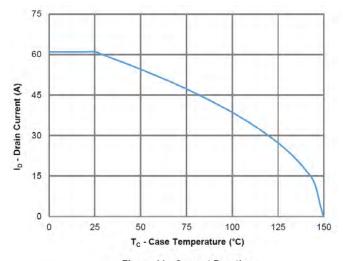


Figure 11: Current Derating

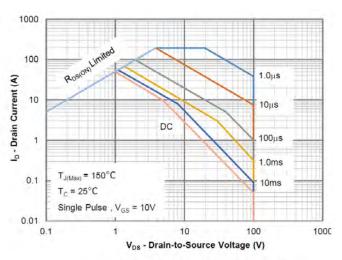


Figure 12: Safe Operating Area



## **Typical Performance Characteristics**

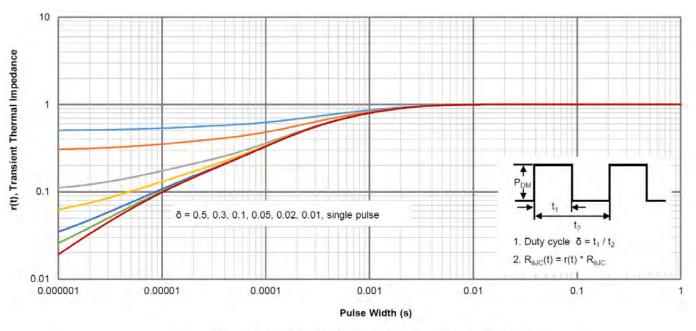
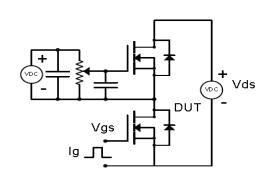


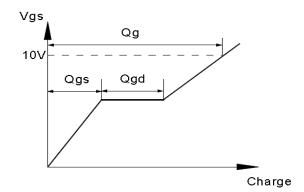
Figure 13: Normalized Maximum Transient Thermal Impedance



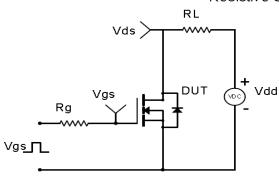
## **Test Circuit & Waveform**

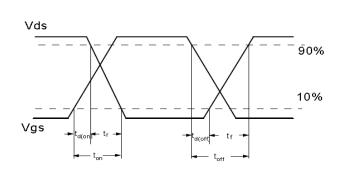
#### Gate Charge Test Circuit & Waveform



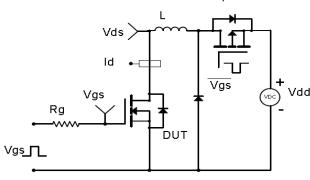


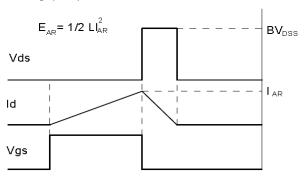
Resistive Switching Test Circuit & Waveforms



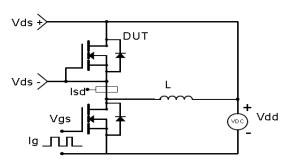


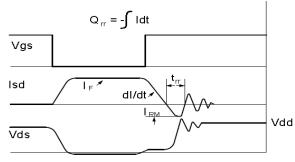
#### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





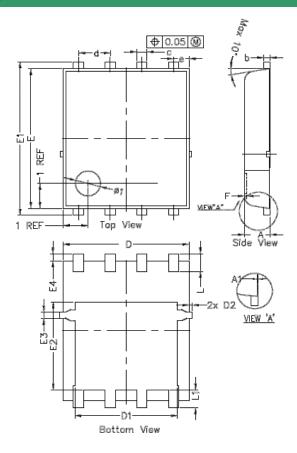
#### Diode Recovery Test Circuit & Waveforms







## **Outline Drawing PDFN5060**



Dim	Millimeters			
	Min	Nom	Max	
А	0.900	1.000	1.100	
A1	0.000		0.050	
b	0.246	0.254	0.312	
С	0.310	0.410	0.510	
d	1.27BSC			
D	4.950	5.050	5.150	
D1	4.000	4.100	4.200	
D2			0.125	
е	0.62BSC			
E	5.500	5.600	5.700	
E1	6.050	6.150	6.250	
E2	3.425	3.525	3.625	
E3	0.150	0.250	0.350	
E4	0.175	0.275	0.375	
F			0.100	
L	0.500	0.600	0.700	
L1	0.600	0.700	0.800	



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